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Serial Interface for Data Converters

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Foreword

The JESD204 standard separates the communication mechanism between logic devices and data converters into three layers, each with a distinct function: physical (specified in clause 5), link (64B/66B and 64B/80B encoding specified clause 0, and 8B/10B encoding specified in clause 0), and transport (specified in clause 0). The JESD204 physical layer encompasses the PMA and PMD Ethernet layers; the JESD204 link layer encompasses the FEC and PCS Ethernet layers and additional CRC and alignment functionality. Finally, the JESD204 transport layer maps to the MAC Ethernet layer (Figure 1).

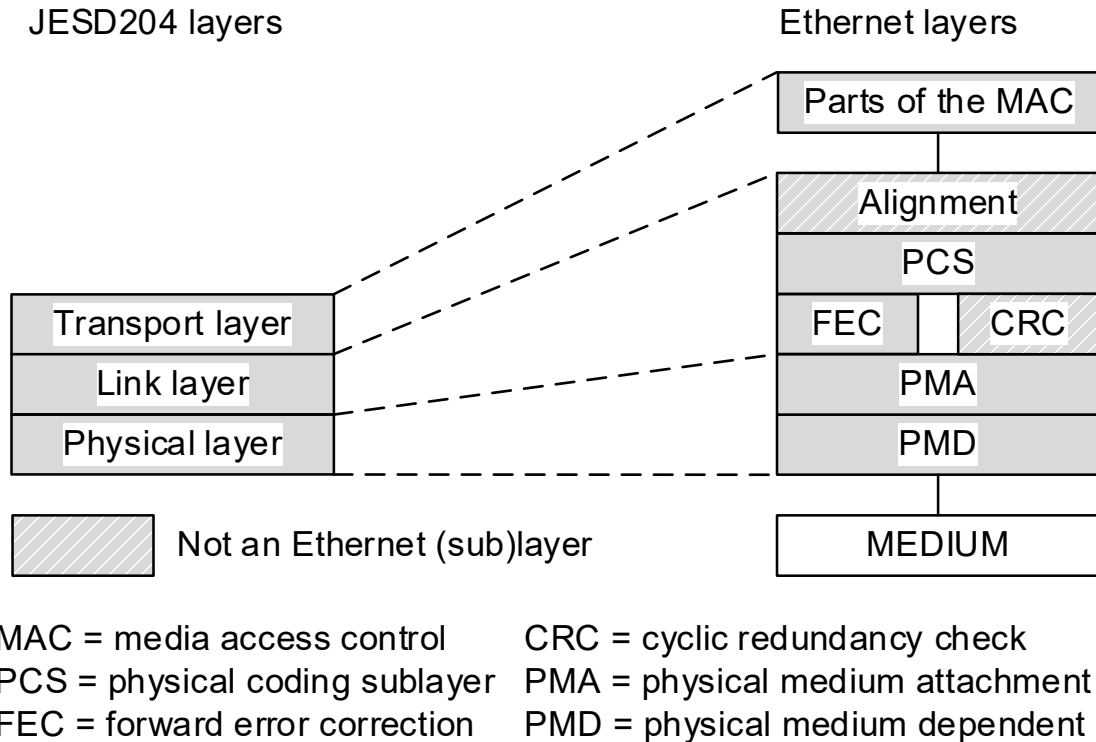


Figure 1 — JESD204 layer relationship to the IEEE Ethernet model

The JESD204C.01 standard replaces JESD204C, which replaced JESD204B standard.

SERIAL INTERFACE FOR DATA CONVERTERS

(From JEDEC Board Ballot JCB-21-56, formulated under cognizance of the JEDEC JC-16 Committee on Interface Technology.)

1 Scope

This standard describes a serialized interface between data converters and logic devices. It contains normative information to enable designers to implement devices that communicate with other devices covered by this specification. Informative annexes are included to clarify and exemplify the document.

Due to the range of applications involved, the intention of this standard is to completely specify only the serial data interface and the link protocol. Certain signals common to both the interface and the function of the device, such as device clocks and control interfaces, have application-dependent requirements. The JESD204 standard does not require a specific implementation of the control interface, however a serial interface is the recommended implementation. Devices may also have application-dependent modes, such as a low power / shutdown mode that will affect the interface. In these instances, the specification merely constrains other device properties as they relate to the interface, and leaves the specific implementation up to the designer.

Revision A of the standard was expanded to support serial data interfaces consisting of single or multiple lanes per converter device. In addition, converter functionality (ADC or DAC) can be distributed over multiple devices:

- All parallel running devices are implemented or specified to run synchronously with each other using the same data format.
- Normally this means that they are part of the same product family.

Revision B of the standard supports the following additional functions:

- Mechanism for achieving repeatable, programmable deterministic delay across the JESD204 link.
- Support for serial data rates up to 12.5 Gbps.
- Transition from using frame clock as the main clock source to using device clock as the main clock source. Device clock frequency requirements offer much more flexibility compared to requiring a frame clock input.

Revision C of the standard now supports the following additional functions:

- Data interfaces up to 32.45 Gbps.
- Three link layers – 64B/66B, 64B/80B, and 8B/10B. The 8B/10B link layer is similar to the link layer defined in JESD204B.